TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOSIII)

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SWITCHING REGULATOR, DC-DC CONVERTER APPLICATIONS

• Low Drain-Source ON Resistance : $R_{DS(ON)} = 15 \Omega$ (Typ.)

• High Forward Transfer Admittance : $|Y_{fs}| = 0.65 \, S$ (Typ.)

• Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 720 \,\text{V}$)

• Enhancement-Mode : $V_{th} = 2.4 \sim 3.4 \text{ V}$

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTE	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$v_{ m DSS}$	900	V	
Drain-Gate Voltage ($v_{ m DGR}$	900	V	
Gate-Source Voltage	$v_{ m GSS}$	±30	V	
DOD	DC (Note 1)	I_{D}	1	A
DCDrain Current	Pulse (Note 1)	$I_{ m DP}$	2	A
Drain Power Dissipat	$P_{\mathbf{D}}$	20	W	
Single Pulse Avalance	EAS	140	mJ	
Avalanche Current	I_{AR}	1	A	
Repetitive Avalanche	EAR	2.0	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	$^{\circ}\mathrm{C}$	
Storage Temperature	$\mathrm{T_{stg}}$	-55~150	°C	

THERMAL CHARACTERISTICS

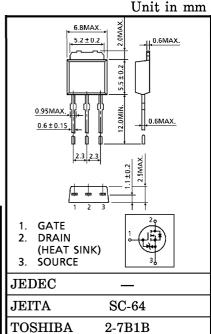
CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R _{th (ch-c)}	6.25	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	125	°C/W

(Note 1): Please use devices on condition that the channel temperature is below 150°C.

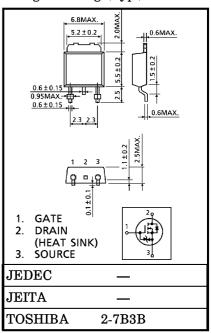
(Note 2) : $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 257 mH $R_G = 25 \Omega$, $I_{AR} = 1 \text{ A}$

(Note 3): Repetitive rating; Pulse Width Limited by Max. junction temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.36g (Typ.)



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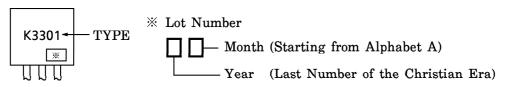
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	I_{GSS}	$V_{GS} = \pm 30 \text{ V}, \ V_{DS} = 0 \text{ V}$	_	_	±10	μ A
Gate-Source : Voltage	Breakdown	V (BR) GSS	$I_{G} = \pm 10 \mu\text{A}, V_{DS} = 0 \text{V}$	±30	_	_	V
Drain Cut-of	f Current	$I_{ m DSS}$	$V_{DS} = 720 \text{ V}, \ V_{GS} = 0 \text{ V}$	_	_	100	μ A
Drain-Source Voltage	Breakdown	V (BR) DSS	$I_{ m D} = 10 \ { m mA}, \ { m V}_{ m GS} = 0 \ { m V}$	900	_	_	V
Gate Thresho	old Voltage	$V_{ m th}$	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	2.4	_	3.4	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$	_	15	20	Ω
Forward Trai	nsfer	Y _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$	0.3	0.65	_	S
Input Capaci	Input Capacitance				165		
Reverse Transfer		C_{rss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		6		рF
_	Capacitance			<u> </u>	21	_	P-
Output Capa	citance	Coss					
Switching Time Fall Time	Rise Time	t _r	V_{GS} V_{OUT}	_	15	_	
	Turn-on Time	t _{on}		_	60	_	na
	Fall Time	tf		_	40	_	ns ns
	Turn-off Time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \ \mu \text{s}$	_	110	_	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q_{g}	$V_{DD} = 400 \text{ V}, V_{GS} = 10 \text{ V},$	_	6	_	~
Gate-Source Charge		Q_{gs}	$I_D = 1A$	_	3	_	nC
Gate-Drain (Gate-Drain ("Miller") Charge				3		

SOURCE-DRAIN RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current (Note 1)	$I_{ m DR}$	_	_	_	1	A
Pulse Drain Reverse Current (Note 1)	$I_{ m DRP}$	_	_	_	2	A
Forward Voltage (Diode)	$ m v_{DSF}$	$I_{\mathrm{DR}} = 1 \mathrm{A}, \ \mathrm{V}_{\mathrm{GS}} = 0 \mathrm{V}$	_	_	-1.7	V
Reverse Recovery Time	t_{rr}	$I_{\mathrm{DR}} = 1 \mathrm{A}, \ \mathrm{V}_{\mathrm{GS}} = 0 \mathrm{V}$		1300		ns
Reverse Recovery Charge	$Q_{\mathbf{rr}}$	$\mathrm{dI}_{\mathrm{DR}}$ / $\mathrm{dt}=100\mathrm{A}$ / $\mu\mathrm{s}$	_	1.95	_	μ C

MARKING



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